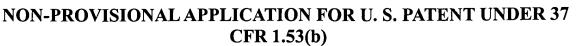


"EXPRESS MAILING" Mailing Label No. EL881899552US. Date of

Deposit: January 30, 2002. I hereby certify that this paper is being

deposited with the U.S. Postal Service, Express Mail Post Office to

Addressee Service under 37 CFR 1.10 on the date shown above and is addressed to the Assistant Commissioner for Patents, Washington, D.C.



TRANSMITTAL FORM

Attorney Docket No.

TI-32857

Assistant Commissioner for Patents Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s):

Baldonado, et al.

For:

METHOD AND SYSTEM OF WIRE BONDING USING INTERPOSER PADS

20231.

Enclosed are:

6 Sheets of informal drawings and 11 pages of Specification (including Abstract)

X A Declaration/Power of Attorney (unsigned)

Assignment with PTO Form 1595

This application claims priority of U.S. Provisional Patent Application No. 60/343,652 filed on December 28, 2001 entitled "Method and System of Wire Bonding Using Interposer Pads," and the teachings are

incorporated herein by reference.

| FEE CALCULATION | | | | | FEE |
|--------------------|--------|-------|-----------------|-----------------|------------------------|
| | NUMBER | | NUMBER EXTRA | RATE | BASIC FEE \$ 740.00 |
| Total Claims | 21 | -20 = | 1 | X \$18 = | 18.00 |
| Independent Claims | 3 | - 3 = | 0 | X \$84 = | 0.00 |
| | 1 | | Te | otal Filing Fee | \$758.00 |

Please charge Deposit Account No. 20-0668 in the amount of the total fees set forth. The Assistant Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 20-0668.

All correspondence related to this application may be addressed to Mike Skrehot, at Texas Instruments

Incorporated, M/S 3999, P. O. BOX 655474, Dallas, TX 75265

Date

Robert C. Klinger, Reg. No. 34,365

-h